



Material Content Data Sheet



Sales Product Name		TLE92108-231QX		Issued		16. July 2019		
MA#		MA005346187						
Package		PG-VQFN-48-31		Weight*		129.55 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.824	2.18	2.18	21796	21796
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		553	
	non noble metal	iron	7439-89-6	1.433	1.11		11063	
	non noble metal	copper	7440-50-8	58.193	44.92	46.10	449207	460961
wire	non noble metal	copper	7440-50-8	0.649	0.50	0.50	5009	5009
encapsulation	organic material	carbon black	1333-86-4	0.187	0.14		1443	
	plastics	epoxy resin	-	7.912	6.11		61073	
	inorganic material	silicondioxide	60676-86-0	54.198	41.84	48.09	418372	480888
leadfinish	non noble metal	tin	7440-31-5	2.596	2.00	2.00	20042	20042
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4738	4738
glue	plastics	epoxy resin	-	0.196	0.15		1510	
	noble metal	silver	7440-22-4	0.655	0.51	0.66	5056	6566
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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